

The RF Line

2.1-2.2 GHz SiFET

RF Integrated Power Amplifier

The MHVIC2115R2 is a 26 Volt integrated power amplifier designed for driver and output stage W-CDMA applications. The device is a three-stage amplifier with input matching using Motorola's high voltage LDMOS IC process. The device is packaged in a PFP-16 power flat pack package that provides excellent thermal performance through a solderable backside contact.

Driver Application

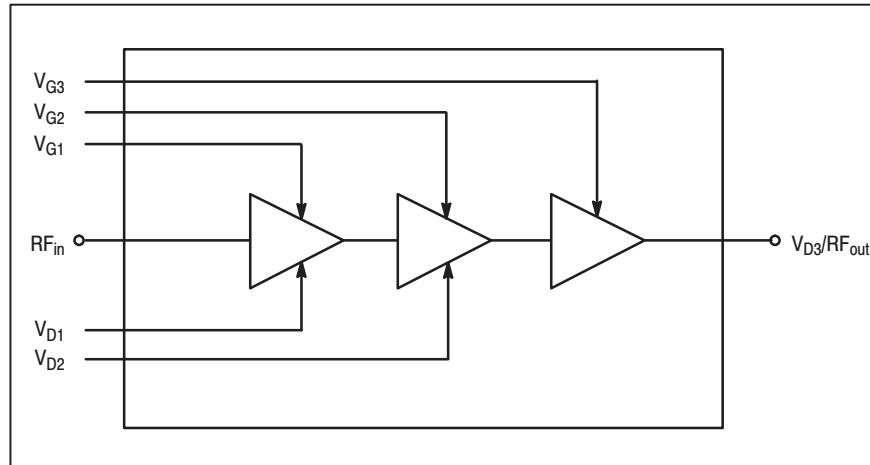
- Typical W-CDMA Performance: -53 dBc ACPR, 2.1–2.2 GHz, 26 Volts, $I_{DQ1} = 96 \text{ mA}$, $I_{DQ2} = 204 \text{ mA}$, $I_{DQ3} = 111 \text{ mA}$, 3GPP Test Model 1, Measured in a 3.84 MHz BW @ 5 MHz offset, 64 DTCH
 - Output Power — 23 dBm
 - Power Gain — 34 dB
- Gain Flatness = 0.3 dB from 2.1–2.17 GHz

Output Application

- Typical W-CDMA Performance: -45 dBc ACPR, 2.1–2.2 GHz, 27 Volts, $I_{DQ1} = 56 \text{ mA}$, $I_{DQ2} = 61 \text{ mA}$, $I_{DQ3} = 117 \text{ mA}$, 3GPP Test Model 1, Measured in a 1.0 MHz BW @ 4 MHz offset, 64 DTCH
 - Output Power — 34 dBm
 - Power Gain — 30 dB
 - PAE = 16%
- P1dB = 15 Watts, Gain Flatness = 0.2 dB from 2.1 to 2.2 GHz
- On-Chip Input Matching to 50 Ohms Impedance
- High Gain and High Linearity
- Integrated ESD Protection
- Temperature Compensation Capability
- Available in Tape and Reel. R2 Suffix = 1,500 Units per 16 mm, 13 inch Reel.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	65	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +15	Vdc
Storage Temperature Range	T_{stg}	-65 to +150	°C
Operating Junction Temperature	T_J	150	°C



MHVIC2115R2

2.2 GHz, 26 V, 23/34 dBm
W-CDMA
RF LDMOS INTEGRATED CIRCUIT



CASE 978-03
PFP-16

PIN CONNECTIONS

N.C.	1	○	16	N.C.
V_{G3}	2		15	V_{D3}/RF_{out}
V_{G2}	3		14	V_{D3}/RF_{out}
V_{G1}	4		13	V_{D3}/RF_{out}
RF_{in}	5		12	V_{D3}/RF_{out}
RF_{in}	6		11	V_{D3}/RF_{out}
V_{D1}	7		10	V_{D3}/RF_{out}
V_{D2}	8		9	N.C.

(Top View)

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$		°C/W
Driver Application ($P_{out} = +0.2$ W CW)	Stage 1, 26 Vdc, $I_{DQ} = 96$ mA Stage 2, 26 Vdc, $I_{DQ} = 204$ mA Stage 3, 26 Vdc, $I_{DQ} = 111$ mA	3.5	
Output Application ($P_{out} = +2.5$ W CW)	Stage 1, 27 Vdc, $I_{DQ} = 56$ mA Stage 2, 27 Vdc, $I_{DQ} = 61$ mA Stage 3, 27 Vdc, $I_{DQ} = 117$ mA	2.7	

ESD PROTECTION CHARACTERISTICS

Test Conditions	Class
Human Body Model	1 (Minimum)
Machine Model	M1 (Minimum)
Charge Device Model	C2 (Minimum)

MOISTURE SENSITIVITY LEVEL

Test Methodology	Rating
Per JESD 22-A113	3

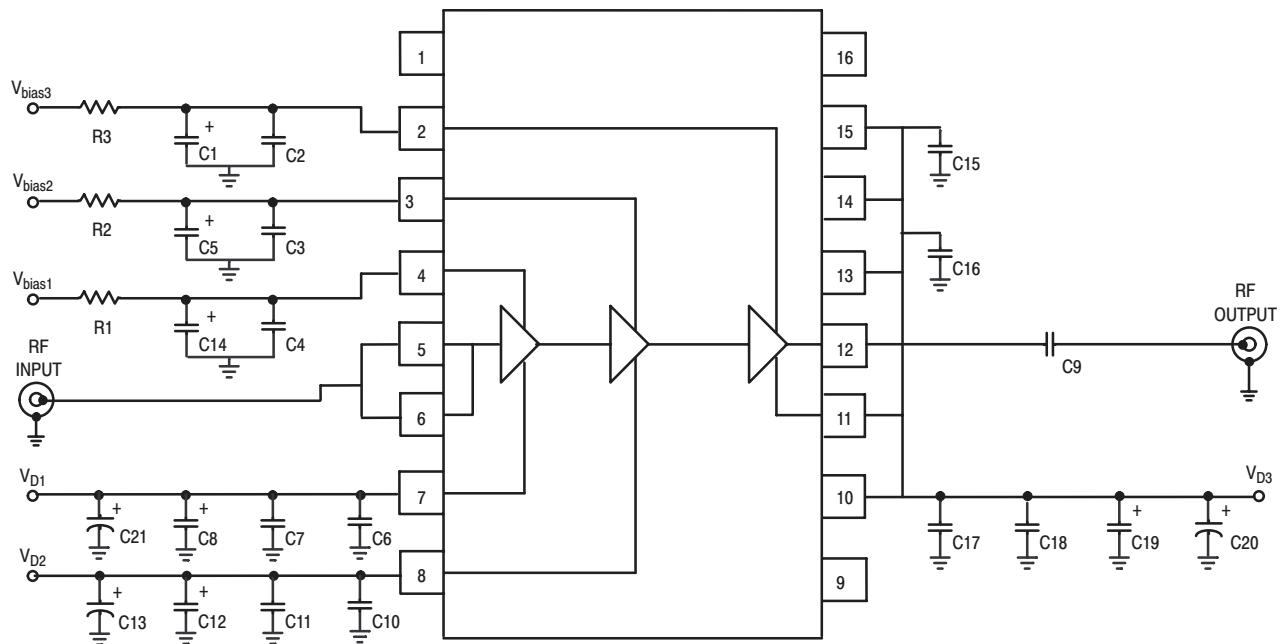
ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ C$, 50 ohm system unless otherwise noted)

W-CDMA CHARACTERISTICS (In Motorola Test Fixture) $V_{DS} = 26$ V, $I_{DQ1} = 96$ mA, $I_{DQ2} = 204$ mA, $I_{DQ3} = 111$ mA, 2.11–2.17 GHz

Characteristic	Symbol	Min	Typ	Max	Unit
Power Gain @ $P_{out} = 23$ dBm	G_{ps}	31	34	—	dB
Gain Flatness @ $P_{out} = 23$ dBm	G_F	—	0.3	0.5	dB
Input Return Loss @ $P_{out} = 23$ dBm	IRL	—	-12	-10	dB
Group Delay	—	—	1.7	—	ns
Phase Linearity	—	—	0.2	—	°
1-Carrier W-CDMA Conditions: Adjacent Channel Power Ratio @ $P_{out} = 23$ dBm, 5 MHz Offset	ACPR	—	-53	-50	dBc
1-Carrier W-CDMA Conditions: Adjacent Channel Power Ratio @ $P_{out} = 28$ dBm, 5 MHz Offset	ACPR	—	-50	—	dBc

W-CDMA CHARACTERISTICS (In Motorola Test Fixture) $V_{DS} = 27$ V, $I_{DQ1} = 56$ mA, $I_{DQ2} = 61$ mA, $I_{DQ3} = 117$ mA, 2.1–2.2 GHz

Characteristic	Symbol	Min	Typ	Max	Unit
Power Gain @ $P_{out} = 34$ dBm	G_{ps}	—	30	—	dB
Gain Flatness @ $P_{out} = 34$ dBm	G_F	—	0.2	—	dB
Input Return Loss @ $P_{out} = 34$ dBm	IRL	—	-12	—	dB
Power Added Efficiency @ $P_{out} = 34$ dBm	PAE	—	16	—	%
1-Carrier W-CDMA Conditions: Adjacent Channel Power Ratio @ $P_{out} = 34$ dBm, 4 MHz Offset	ACPR	—	-45	—	dBc



C1, C5, C8, C12, C14, C19
 C2, C3, C4, C7, C11, C18
 C6, C10, C17
 C9, C15, C16

1 μ F SMT Tantalum Chip Capacitors
 0.01 μ F Chip Capacitors (0805C103K5RACTR)
 6.8 pF Chip Capacitors, ACCU-P (AVX 08051J6R8BBT)
 1.8 pF Chip Capacitors, ACCU-P (AVX 08051J1R8BBT)

C13, C20, C21 330 μ F Electrolytic Capacitors
 (MCR35V337M10X16)
 R1, R2, R3 1 k Ω Chip Resistors (0805)
 PCB Arlon, 20 mils, $\epsilon_r = 2.55$

Figure 1. 2.2 GHz Demo Board Schematic

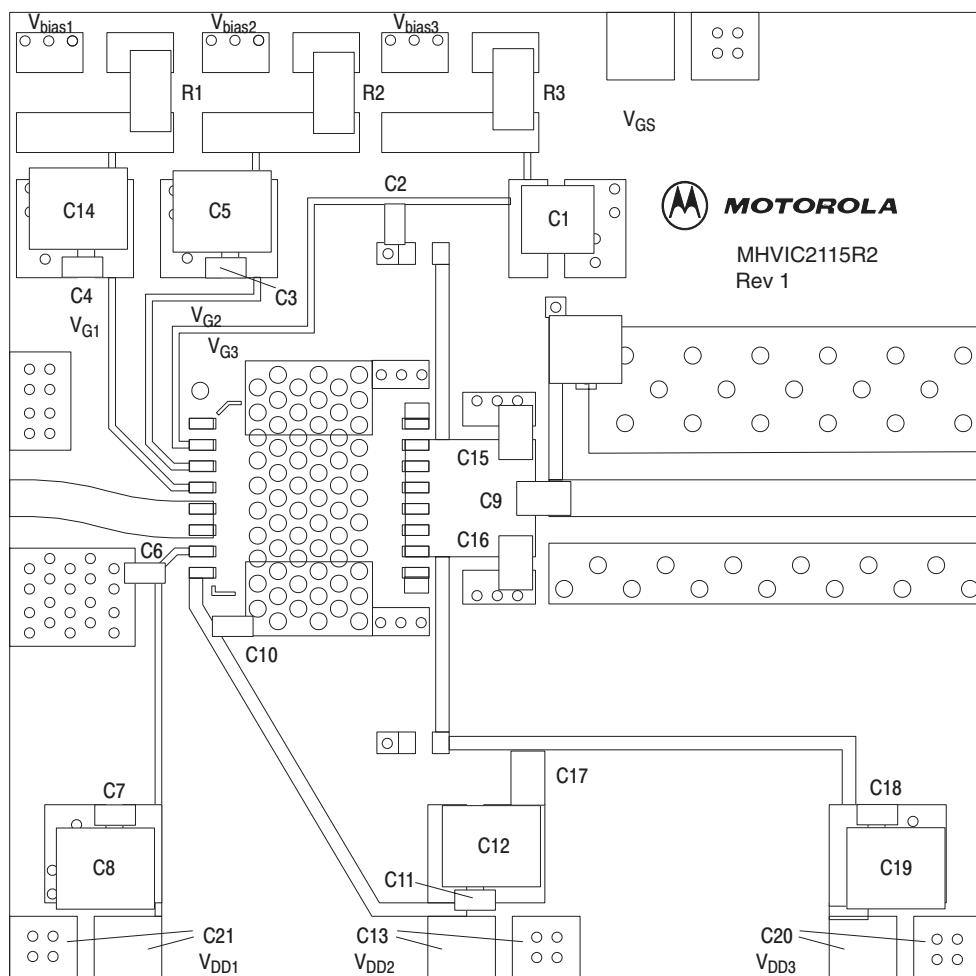


Figure 2. 2.2 GHz Demo Board Component Layout

TYPICAL CHARACTERISTICS

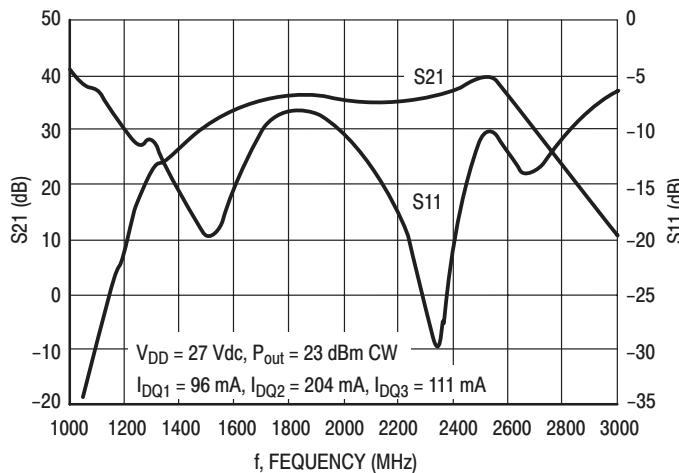


Figure 3. Broadband Frequency Response

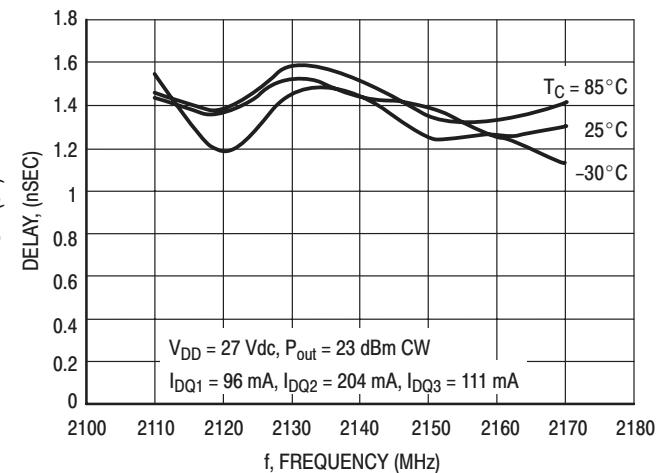


Figure 4. Delay versus Frequency

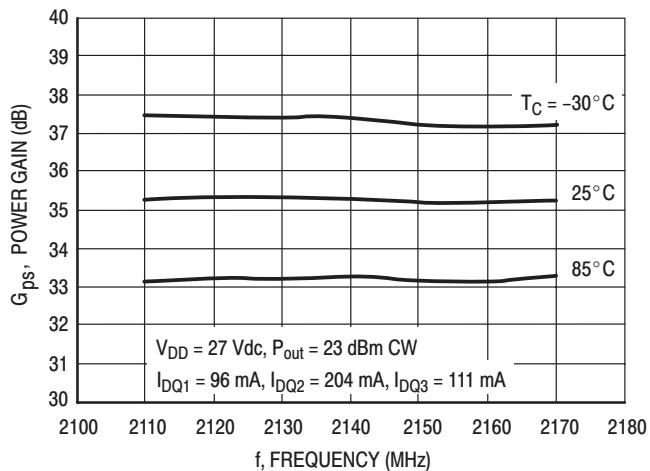


Figure 5. Power Gain versus Frequency

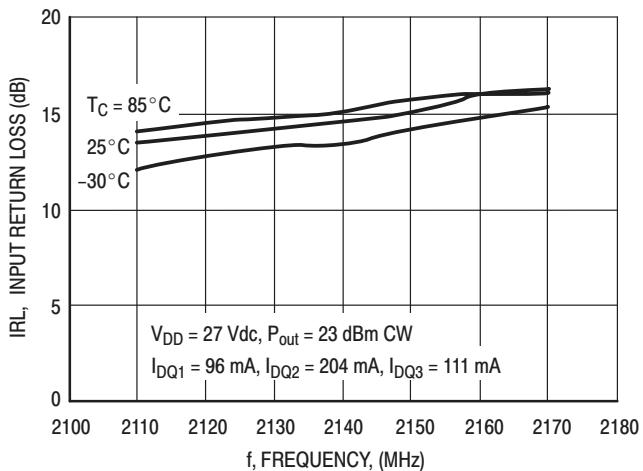


Figure 6. Input Return Loss versus Frequency

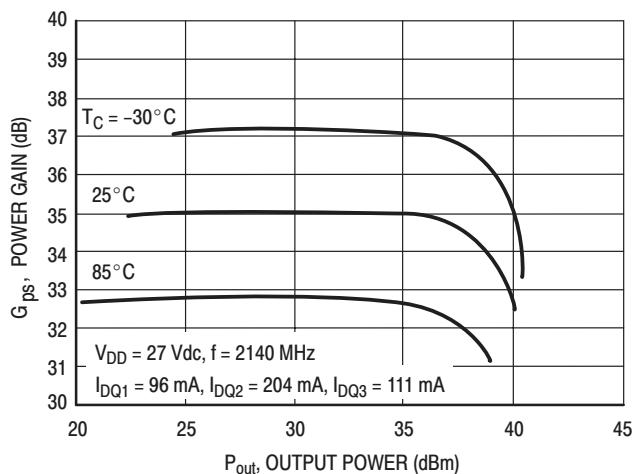


Figure 7. Power Gain versus Output Power

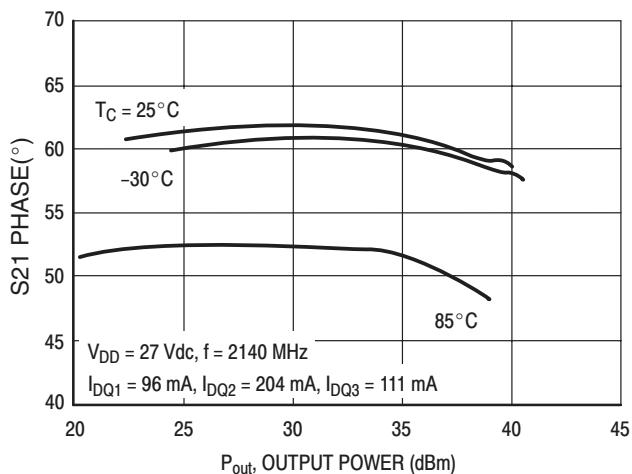
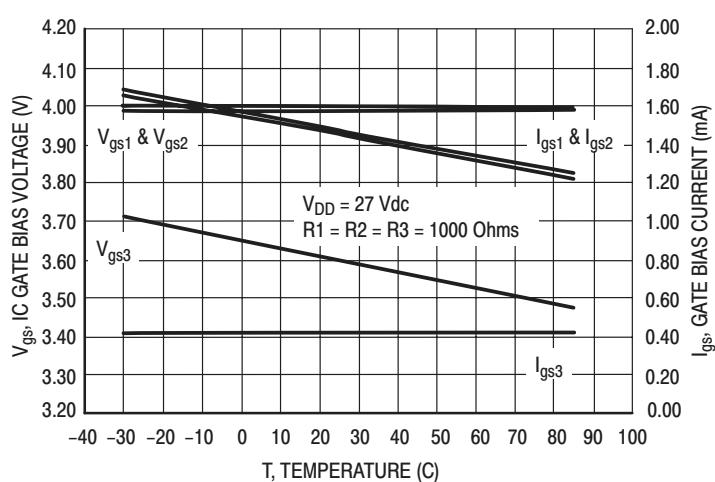
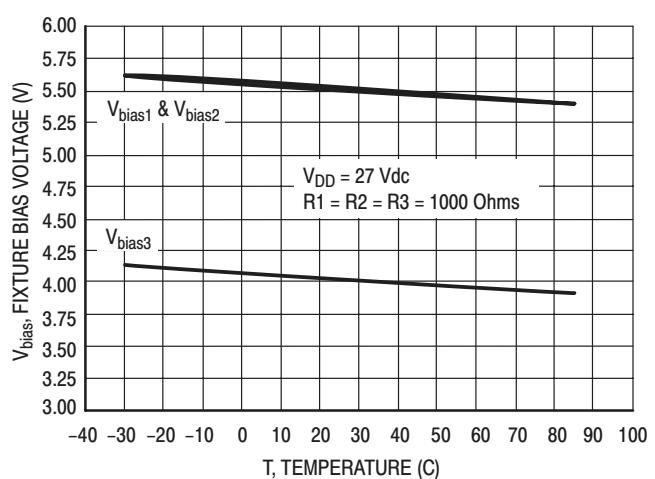
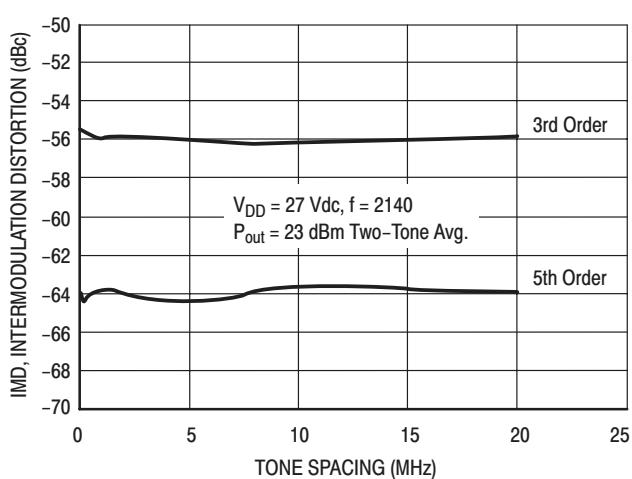
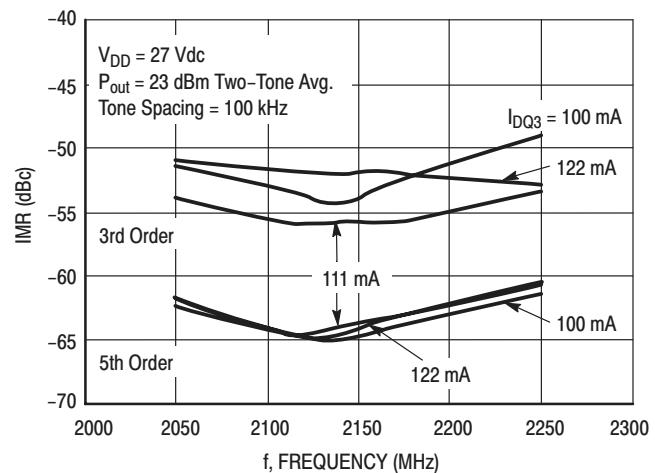
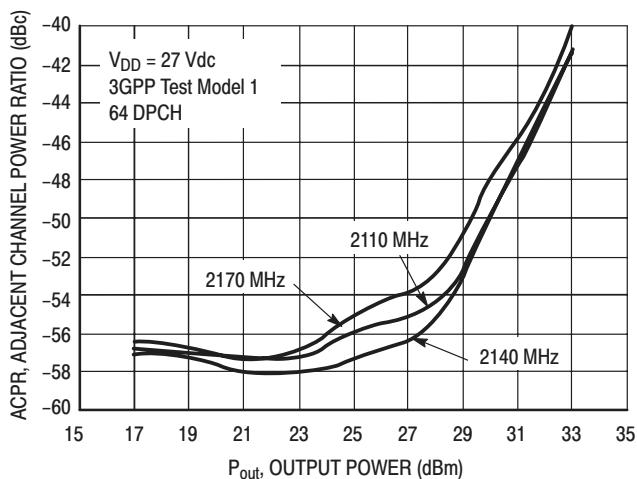


Figure 8. S21 Phase versus Output Power

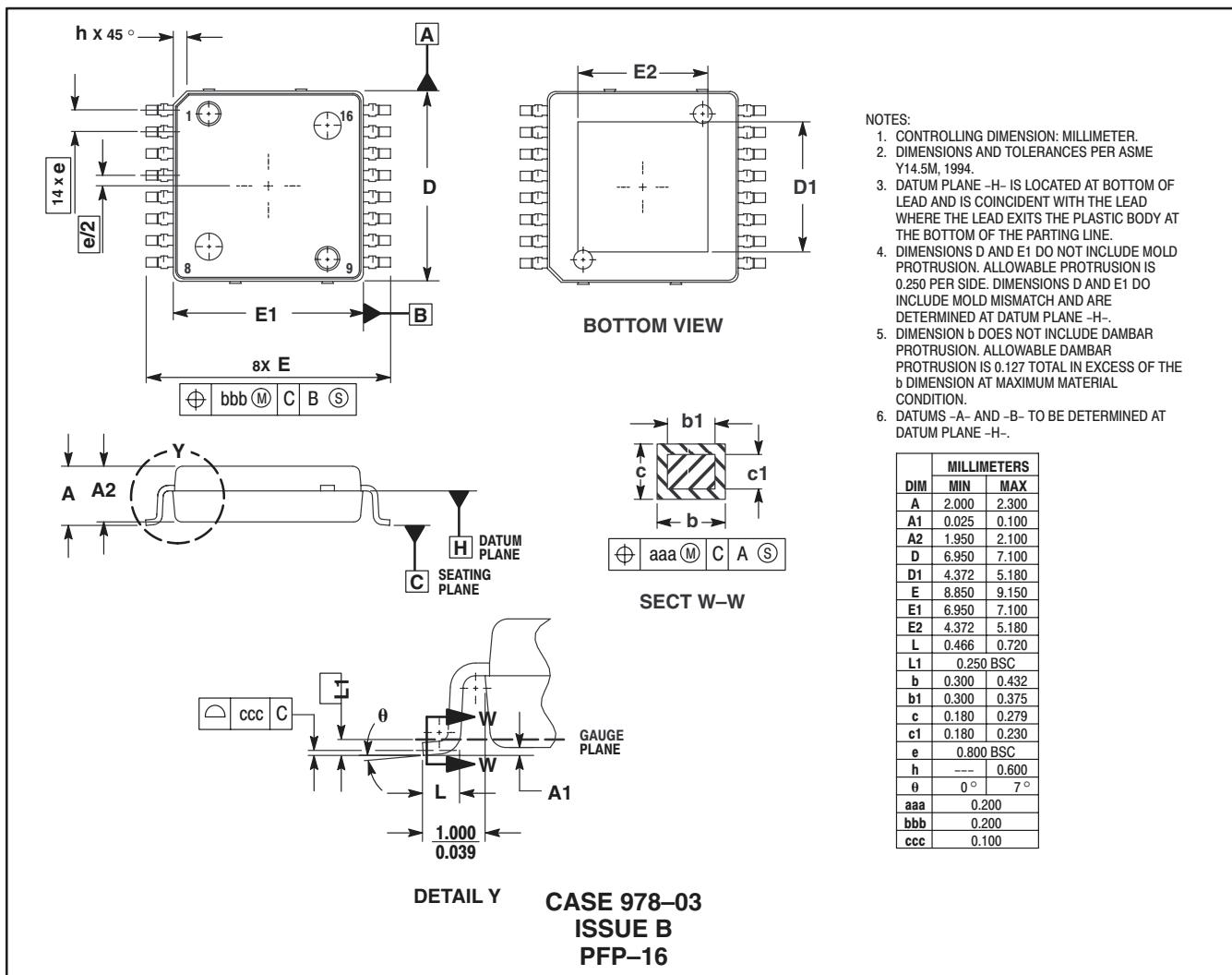
TYPICAL CHARACTERISTICS



NOTES

NOTES

PACKAGE DIMENSIONS



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Motorola Literature Distribution
P.O. Box 5405, Denver, Colorado 80217
1-800-521-6274 or 480-768-2130

JAPAN: Motorola Japan Ltd.; SPS, Technical Information Center,
3-20-1, Minami-Azabu, Minato-ku, Tokyo 106-8573, Japan
81-3-3440-3569

ASIA/PACIFIC: Motorola Semiconductors H.K. Ltd.; Silicon Harbour Centre,
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852-26668334

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